OBSOLETE PRODUCT POSSIBLE SUBSTITUTE PRODUCT HA-5104

CA5470

May 2001

Quad, 14MHz, Microprocessor BiMOS-E Operational Amplifier with MOSFET Input/Bipolar Output

Features

- High Speed CMOS Input Stage Provides
 - Very High Z_I.....5TΩ (5 x 10¹²Ω) (Typ)
 - Very Low II.....0.5pA (Typ) at 5V Operation
 - Very Low I_{IO}0.5pA (Typ) at 5V Operation
- ESD Protection to 2000V
- 3V to 16V Power Supply Operation
- Fully Guaranteed Specifications Over Full Military Range
- Wide BW (14MHz); High SR (5V/ μ s) at 5V Supply
- Wide VICR Range From -0.5V to 3.7V (Typ) at 5V Supply
- Ideally Suited for CMOS and HCMOS Applications

Applications

- Bar Code Readers
- Photodiode Amplifiers (IR)
- Microprocessor Buffering
- Ground Reference Single Supply Amplifiers
- Fast Sample and Hold
- Timers
- Voltage Controlled Oscillators
- Voltage Followers
- V to I Converters
- Peak Detectors
- Precision Rectifiers
- 5V Logic Systems
- 3V Logic Systems

Pinout



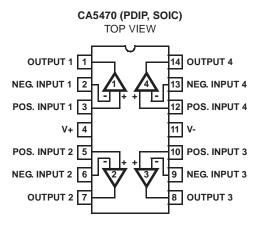
The CA5470 is an operational amplifier that combines the advantages of both high speed CMOS and bipolar transistors on a single monolithic chip. It is constructed in the BiMOS-E process which adds drain-extension implants to 3μ m polygate CMOS, enhancing both the voltage capability and providing vertical bipolar transistors for broadband analog/digital functions. This process lends itself easily to high speed operational amplifiers, comparators, analog switches and interface peripherals, resulting in twice the speed of the conventional CMOS transistors having similar feature size.

BiMOS-E are broadbased bipolar transistors that have high transconductance, gains more constant with current level, stable "precision" base-emitter offset voltages and superior drive capability. Excellent interface with environmental potentials enable use in 5V logic systems and future 3.3V logic systems. Refer to Application Note AN8811.

ESD capability exceeds the standard 2000V level. The CA5470 series can operate with single supply voltages from 3V to 16V or \pm 1.5V to \pm 8V. They have guaranteed specifications at both 5V and \pm 7.5V at room temperature as well as over the full -55°C to 125°C military range.

Part Number Information

PART NUMBER (BRAND)	TEMP. RANGE (^o C)	PACKAGE	PKG. NO.
CA5470E	-55 to 125	14 Ld PDIP	E14.3
CA5470M (5470)	-55 to 125	14 Ld SOIC	M14.15
CA5470M96 (5470)	-55 to 125	14 Ld SOIC Tape and Reel	M14.15



Absolute Maximum Ratings

DC Supply Voltage (Between V+ And V- Terminals) 16V
Differential Input Voltage 8V
Input Voltage
Input Current
Output Short Circuit Duration (Note 1) Indefinite

Operating Conditions

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (^o C/W)
PDIP Package	80
SOIC Package	175
Maximum Junction Temperature (Die)	175 ⁰ C
Maximum Junction Temperature (Plastic Package)	
Maximum Storage Temperature Range65	^o C to 150 ^o C
Maximum Lead Temperature (Soldering 10s)	300 ⁰ C
(SOIC - Lead Tips Only)	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

1. Short circuit may be applied to ground or to either supply.

2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications	Typical Values Intended Only for Design	gn Guidance at V+ = 5V, V- = 0V, $T_A = 25^{\circ}C$, Unless Otherwise Specified	
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PARAMETER	SYMBOL	TEST CONDITIONS	TYPICAL VALUES	UNITS
Input Resistance	RI		5	TΩ
Input Capacitance	Cl	f = 1MHz	3.1	pF
Unity Gain Crossover Frequency	f _T		14	MHz
Slew Rate	SR	$V_{OUT} = 3.65 V_{P-P}$	5	V/µs
Transient Response: Rise Time/Fall Time	t _r	$C_L = 25pF, R_L = 2k\Omega$ (Voltage Follower)	27/25	ns
Overshoot	OS	1	20	%
Settling Time (To <0.1%, $V_{IN} = 4V_{P-P}$)	ts	$C_L = 25 pF, R_L = 2k\Omega$ (Voltage Follower)	1	μs
Full Power BW, SR = $5V/\mu s$	FPBW	A _V = 1, V _{OUT} = 3.65V _{P-P}	436	kHz

Electrical Specifications $T_A = 25^{\circ}C$, V+ = 5V, V- = GND

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Input Offset Voltage	V _{IO}		-	6	22	mV
Input Offset Current	lliol		-	0.5	50 (Note 3)	pА
Input Current	Ц		-	0.5	50 (Note 3)	pА
Common Mode Input Range	V _{ICR}		3.5	-0.5 to 3.7	0	V
Common Mode Rejection Ratio	CMRR	V _{ICR} = 0V to 3.5V	55	70	-	dB
Power Supply Rejection Ratio	PSRR	$\Delta V = 2V$	60	75	-	dB
Positive Output Voltage Swing	V _{OM} +	$R_L = 2k\Omega$ to GND	4	4.4	-	V
Negative Output Voltage Swing	V _{OM} -	$R_L = 2k\Omega$ to GND	-	0.06	0.10	V
Total Supply Current	I _{SUPPLY}	V_{OUT} = 2.5V, R_{L} = ∞	-	6	7	mA
Unity Gain Bandwidth Product	fT		10	14	-	MHz
Slew Rate	SR		4	5	-	V/µs
Output Current						
Source to opposite supply	ISOURCE		4	5.5	-	mA
Sink to opposite supply	I _{SINK}	7	1.0	1.2	-	mA
Open Loop Gain	A _{OL}	0.5V to 3.5V, $R_L = 10k\Omega$	80	90	-	dB

NOTE:

3. This is the lowest value that can be tested reliably. Almost all devices will be <10pA.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Input Offset Voltage	V _{IO}		-	6	25	mV
Input Offset Current	I _{IO}		-	550	5500	pА
Input Current	Ц		-	550	11000	pА
Common Mode Input Range	V _{ICR}		3.5	-0.5 to 3.7	0	V
Common Mode Rejection Ratio	CMRR	V _{ICR} = 0V to 3.5V	50	65	-	dB
Power Supply Rejection Ratio	PSRR	$\Delta V = 2V$	58	75	-	dB
Positive Output Voltage Swing	V _{OM} +	$R_L = 2k\Omega$ to GND	3.8	4.2	-	V
Negative Output Voltage Swing	V _{OM} -	$R_L = 2k\Omega$ to GND	-	0.08	0.11	V
Total Supply Current	ISUPPLY	V _{OUT} = 2.5V	-	9	11	mA
Unity Gain Bandwidth Product	f _T		8	12	-	MHz
Slew Rate	SR		3	5	-	V/µs
Output Current				1		
Source to opposite supply	ISOURCE		4	5.5	-	mA
Sink to opposite supply	I _{SINK}		0.8	1.2	-	mA
Open Loop Gain	A _{OL}	0.5V to 3.5V, $R_L = 10k\Omega$	80	90	- 1	dB
Electrical Specifications T, PARAMETER	_A = 25°C, V _{SUPPL} SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Input Offset Voltage	V _{IO}		-	5	25	mV
Input Offset Current	I _{IO}		-	0.5	50 (Note 4)	pА
Input Current	Ц		-	1	50 (Note 4)	pА
Common Mode Input Range	VICR		5.8	-7.8 to 6.0	-7.5	V
Common Mode Rejection Ratio	CMRR	V _{ICR} = 0V to 13.3V	60	70	- 1	dB
Power Supply Rejection Ratio	PSRR	$\Delta V = 1 V$	60	76	- 1	dB
Positive Output Voltage Swing	V _{OM} +					
	0	$R_L = 2k\Omega$ to GND	6.3	6.5	-	V
		$R_L = 10k\Omega$ to GND	6.4	6.6	-	V
Negative Output Voltage Swing	V _{OM} -		-			
i togali to o alpart i ollago o lling	- 010	$R_{I} = 2k\Omega$ to GND	-	-2.6	-2	V
		$R_L = 10k\Omega$ to GND	-	-7.3	-7.1	V
Total Supply Current		$V_{OUT} = GND, R_L = \infty$	-	-7.3	-7.1	
Unity Gain Bandwidth Product	I _{SUPPLY}	vOUT = GND, KL = ∞				mA
	fT		12	16	-	MHz
Slew Rate	SR		4	7	-	V/µs
Output Current						
Source to opposite supply	ISOURCE		6.2	6.8	-	mA
Sink to opposite supply	ISINK		1	1.4	-	mA

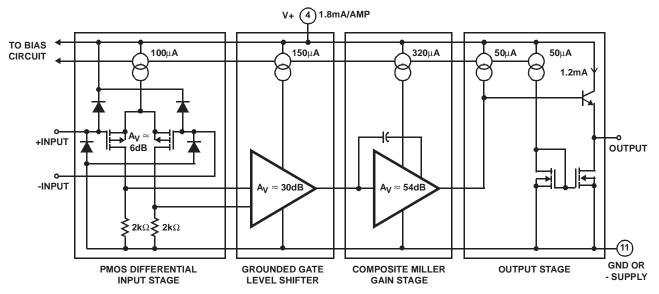
NOTE:

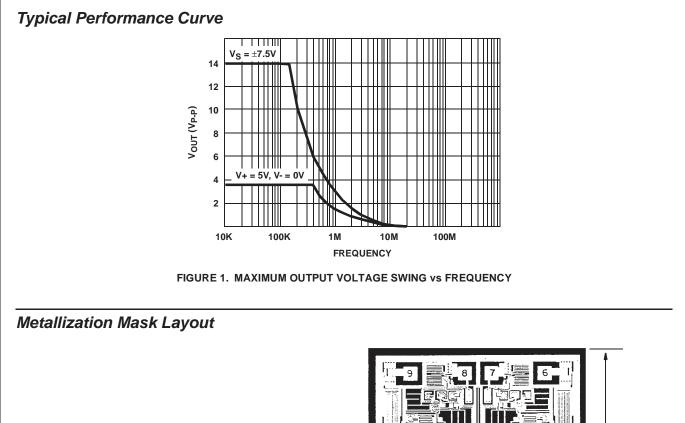
4. This is the lowest value that can be tested reliably. Almost all devices will be <10pA.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Input Offset Voltage	IV _{IO} I		-	5	30	mV
Input Offset Current	I _{IO}		-	550	5500	pА
Input Current	lı		-	1100	11000	pА
Common Mode Input Range	VICR		5.8	-7.8 to 6.0	-7.5	V
Common Mode Rejection Ratio	CMRR	V _{ICR} = 0V to 3.5V	58	70	-	dB
Power Supply Rejection Ratio	PSRR	$\Delta V = 1V$	60	76	-	dB
Positive Output Voltage Swing	V _{OM} +					
		$R_L = 2k\Omega$ to GND	4.75	5.5	-	V
		$R_L = 10k\Omega$ to GND	6.1	6.4	-	V
Negative Output Voltage Swing	V _{OM} -					
		$R_L = 2k\Omega$ to GND	-	-2.6	-2	V
		$R_L = 10k\Omega$ to GND	-	-7.3	-7.1	V
Total Supply Current	ISUPPLY	$V_{OUT} = GND, R_L = \infty$	-	12	18	mA
Unity Gain Bandwidth Product	f _T		10	15	-	MHz
Slew Rate	SR		3	7	-	V/µs
Output Current						
Source to opposite supply	ISOURCE		6.2	6.8	-	mA
Sink to opposite supply	ISINK	1	1	1.4	-	mA
Open Loop Gain	A _{OL}	-5V to +5V, $R_L = 10k\Omega$	80	90	-	dB

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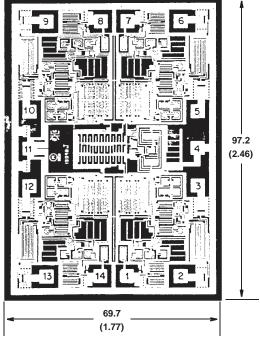
Block Diagram (1/4 of CA5470)





Dimensions in parentheses are in millimeters and derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .

The layout represents a chip when it is part of the wafer. When the wafer is cut into chips, the cleavage angles are 57° instead of 90° with respect to the face of the chip. Therefore, the isolated chip is actually 7 mils (0.17mm) larger in both dimensions.



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Sales Office Headquarters

NORTH AMERICA

Intersil Corporation 2401 Palm Bay Rd. Palm Bay, FL 32905 TEL: (321) 724-7000 FAX: (321) 724-7240

EUROPE Intersil SA Mercure Center 100, Rue de la Fusee 1130 Brussels, Belgium TEL: (32) 2.724.2111 FAX: (32) 2.724.22.05

ASIA Intersil Ltd. 8F-2, 96, Sec. 1, Chien-kuo North, Taipei, Taiwan 104 Republic of China TEL: 886-2-2515-8508 FAX: 886-2-2515-8369